



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20160804000
Datasheet for INA826
Change Notification**

Date: 8/12/2016
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Change Notification Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA826AID	null
INA826AIDGKR	null
INA826AIDGK	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20160804000	PCN Date:	8/12/2016
Title:	Datasheet for INA826		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	11/12/2016		
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



INA826

SBOS562F –AUGUST 2011–REVISED JULY 2016

Changes from Revision E (April 2013) to Revision F

Page

• Added Device Information table, ESD Ratings table, Recommended Operating Conditions table, Feature Description section, Device Functional Modes section, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section	1
• Added TI Design	1
• Changed 2.7-V to 3-V in document title	1
• Changed MSOP to VSSOP, SO to SOIC, and DRG to WSON throughout document	1
• Changed Supply Range Features bullet minimum voltage levels	1
• Changed Packages Features bullet	1
• Changed page 1 graphic	1
• Changed Description section for minor rewording, renaming of packages , and changing single supply voltage value from 2.7 V to 3 V	1
• Changed title of Device Comparison Table	4
• Deleted DGK Package/Package/Ordering Information table	4
• Changed Temperature parameter symbols in Absolute Maximum Ratings table	5
• Changed Input, Differential impedance and Common-mode impedance parameter symbols in Electrical Characteristics table	6
• Changed Input, V_{CM} parameter test conditions in Electrical Characteristics table	6
• Deleted Gain, Range of gain parameter symbol from Electrical Characteristics table	7
• Changed Power Supply, V_S parameter test conditions and minimum specifications in Electrical Characteristics table	7
• Changed V_S voltage to 3.0 V and red V_{REF} trace to 1.5 V in Figure 9 and Figure 10	9
• Changed V_S voltage level to 3.0 V in Figure 29	12
• Changed blue V_S trace value to 3.0 V in Figure 36	13
• Changed conditions of Figure 47 and Figure 48	15
• Changed 2.7 V to 3 V and 1.35 V to 1.5 V in Operating Voltage section	24
• Changed TINA-TI simulation circuit links in Using TINA-TI SPICE-Based Analog Simulation Program with the INA826 section	29

The datasheet number will be changing.

Device Family	Change From:	Change To:
INA826	SBOS562E	SBOS562F

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/INA826>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

INA826AID	INA826AIDGK	INA826AIDGKR	INA826AIDR
INA826AIDRGR	INA826AIDRGT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com